

MOVI NAND Code Information(1/3)

Last Updated : November 2008

K M X X X X X X X X - X X X X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. MOVI NAND/MCP : M

3. Small Classification

- A : NAND + MCU
- B : NAND + NAND + MCU
- C : NAND + NAND + NAND + NAND + MCU
- D : NAND + NAND + NAND + MCU
- H : NAND + NAND + NAND + NAND + NAND + NAND + NAND + NAND + MCU
- X : moviNAND + NAND + SDRAM
- Y : moviNAND + OneNAND + SDRAM
- Z : moviNAND + NAND + SDRAM + SDRAM

4. MoviNAND Density & Vcc & Org. & BB

Code	moviNAND Den	NAND Den	Cell	Vcc	Vccq	Org
0	None					
A	512MByte	2G*2	SLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
B	1GByte	2G*4	SLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
C	2GByte	4G*4	SLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
D	2GByte	8G*2	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
E	4GByte	8G*4	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
F	1GByte	8G*1	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
G	1GByte	4G*2	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
H	3GByte	8G*3	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
I	512MByte	4G*1	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
J	8GByte	8G*8	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
K	2Byte	16G*1	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
L	4GByte	16G*2	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
M	8GByte	16G*4	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
N	12GByte	16G*6	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
O	16GByte	16G*8	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
P	256MByte	2G*1	MLC	2.7V ~ 3.6V	2.7V ~ 3.6V	x8
Q	128MByte	1G*1	SLC	2.7V~3.6V	2.7V~3.6V	x8

MOVI NAND Code Information(2/3)

Last Updated : November 2008

K M X X X X X X X X - X X X X X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

5. LSI

A : S3C49RAX01 D : S3C49NBX01
 E : S3C49VCX01 F : S3C49VCX02
 G : S3C49VCX03 N : S3C49VAX03

6. NOR Flash Density & Vcc & Org.

Code	Den	Vcc	Vccq	Org	Type	Opt
0	NONE					

7. NAND/OneNAND Density & Vcc & Org.

Code	Den	Vcc	Vccq	Org	Opt
0	NONE				
A	2G	1.8V	1.8V	x8	SLC
B	1G OneNAND	1.8V	1.8V	x16	Muxed
C	1G OneNAND	1.8V	1.8V	x16	-
D	2G NAND_0	1.8V	1.8V	x8	-
E	512M	2.7V	2.7V	x8	-
F	2G NAND_0	1.8V	1.8V	x16	SLC

8. UtRAM/SRAM Density & Vcc & Org.

Code	Den	Vcc	Vccq	Org	Opt
0	NONE				

9. DRAM I/F & Density & Vcc & Org.

Code	I/F	Den	Vcc	Vccq	Org	Opt
0	NONE					
A	MDDR*2	1G+512M	1.8V	1.8V	x32	-
B	MDDR*2	512M*2	1.8V	1.8V	x32	-
C	MDDR	1G	1.8V	1.8V	x32	-
D	MDDR*2	1G*2	1.8V	1.8V	x32	-
E	SDR	256M	1.8V	1.8V	x32	-
F	MDDR	1G	1.8V	1.8V	x16	-

10. Generation

M : 1st Generation A : 2nd Generation
 B : 3rd Generation C : 4th Generation

11. "-"

12. Package

A : FBGA (Halogen-Free, Lead-Free)
 B : FBGA (Halogen-Free, OSP Lead-Free)
 D : FBGA (Lead-Free) E : LGA (NO Ball)
 F : FBGA H : LGA (Lead-Free)
 P : FBGA (OSP) Q : TSOP (Lead-Free)
 S : FBGA (OSP Lead-Free)
 Y : FBGA (MoviNAND Special 2)
 Z : FBGA (MoviNAND Special 1)

13~15. Serial Number

(13) Chip Qty

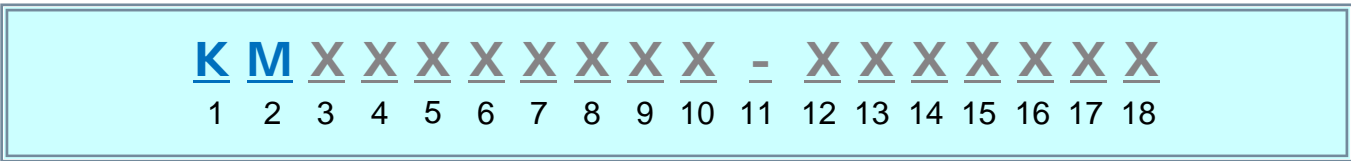
1 : 1chip 2 : 2chip
 3 : 3chip 4 : 4chip
 5 : 5chip 6 : 6chip

(14)~(15) Serial Number

300 : 19ns, 12ns, 7.5ns
 301 : 19ns, 42ns, 7.5ns
 302 : 19ns, 12ns, 6ns
 400 : 19ns(2), 42ns, 7.5ns
 401 : 19ns, 42ns, 6ns, 6ns
 402 : 19ns(2), 42ns, 6ns
 403 : 19ns(2), 12ns, 6ns
 500 : 19ns(2), 42ns, 6ns, 6ns
 501 : 19ns(2), 42ns, 7ns, 6ns
 600 : 19ns(4), 42ns, 7.5ns
 601 : 19ns(4), 42ns, 6ns
 700 : 19ns, 42ns, 7.5ns, 7.5ns
 701 : 19ns(4), 42ns, 6ns, 6ns
 998 : moviNAND Normal
 999 : Daisychain Sample

MOVI NAND Code Information(3/3)

Last Updated : November 2008



16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"